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(12) United States Design Patent
Hara

(10) **Patent No.: US D971,863 S**
(45) **Date of Patent: ** Dec. 6, 2022**

(54) **SEMICONDUCTOR MODULE**

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(73) Assignee: **ROHM CO., LTD.**, Kyoto (JP)

(**) Term: **15 Years**

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(22) Filed: **Jul. 21, 2020**

(30) **Foreign Application Priority Data**

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Jan. 28, 2020 (JP) .... 2020-001387 D

(51) **LOC (13) Cl.** **13-03**
(52) **U.S. Cl.**
USPC **D13/182**
(58) **Field of Classification Search**
USPC D13/123, 133, 146, 147, 158, 182, 184, D13/199
CPC H01L 28/06; H01L 28/07; H01L 28/08; H01L 25/07; H01L 25/16; H01L 25/18; H01L 23/00; H01L 23/31; H05K 1/18; H05K 7/00; H05K 7/20; H02M 7/00
See application file for complete search history.

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(74) *Attorney, Agent, or Firm* — Hamre, Schumann, Mueller & Larson, P.C.

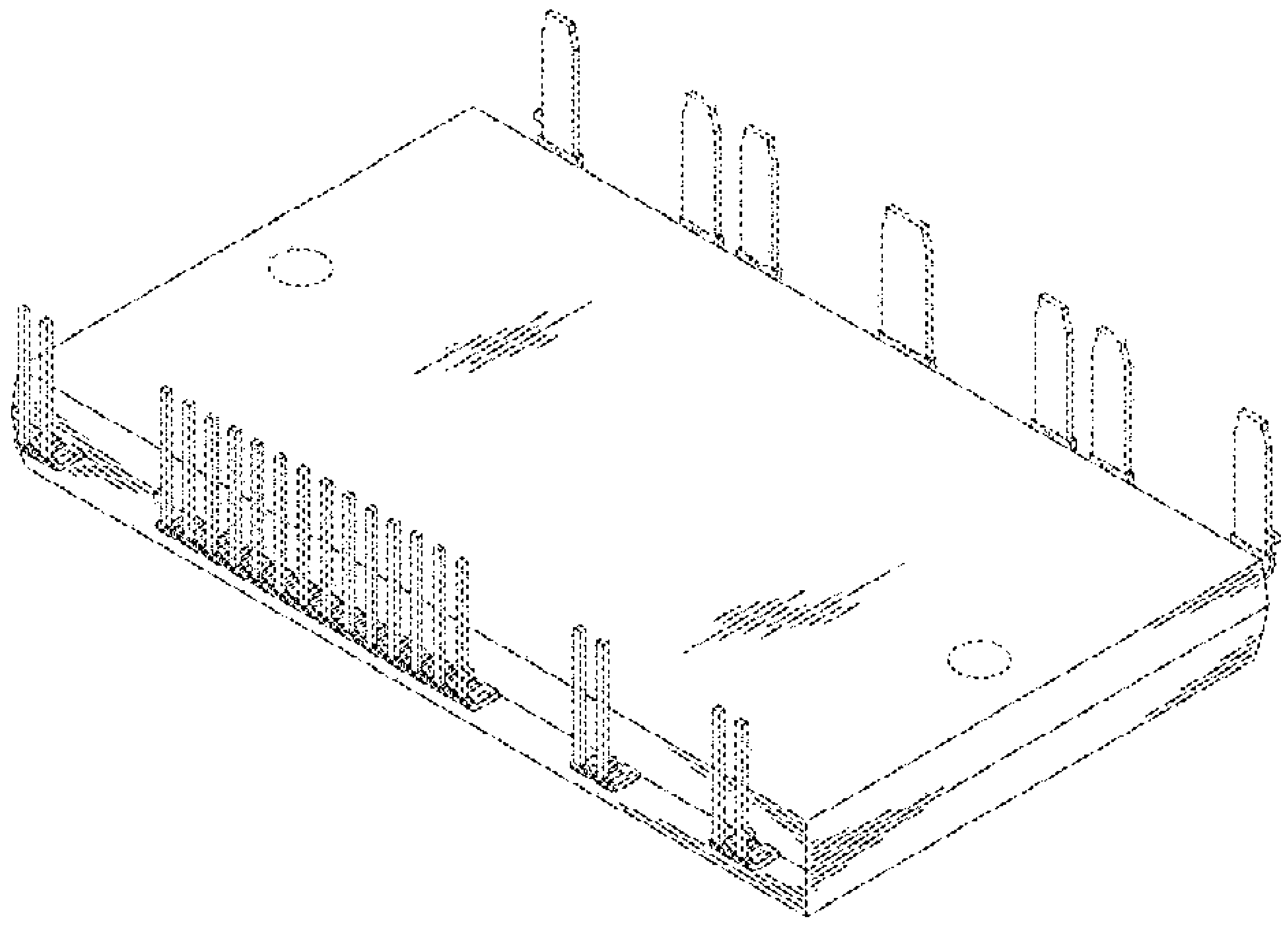
(57) **CLAIM**

The ornamental design for a semiconductor module, as shown and described.

DESCRIPTION

FIG. **1** is a front, top and right side perspective view of a first embodiment of a semiconductor module showing my new design;
FIG. **2** is a rear, bottom and left side perspective view thereof;
FIG. **3** is a front view thereof;
FIG. **4** is a rear view thereof;
FIG. **5** is a top plan view thereof;
FIG. **6** is a bottom plan view thereof;
FIG. **7** is a right side view thereof, the left side view being a mirror image of FIG. **7**;
FIG. **8** is a front, top and right side perspective view of a second embodiment of a semiconductor module showing my new design;
FIG. **9** is a rear, bottom and left side perspective view thereof;
FIG. **10** is a front view thereof;
FIG. **11** is a rear view thereof;
FIG. **12** is a top plan view thereof;
FIG. **13** is a bottom plan view thereof; and,
FIG. **14** is a right side view thereof, the left side view being a mirror image of FIG. **14**.
The broken lines illustrate portions of the semiconductor module that form no part of the claimed design. The dash-dotted lines denote the boundary of the claim and form no part of the claimed design.

1 Claim, 14 Drawing Sheets



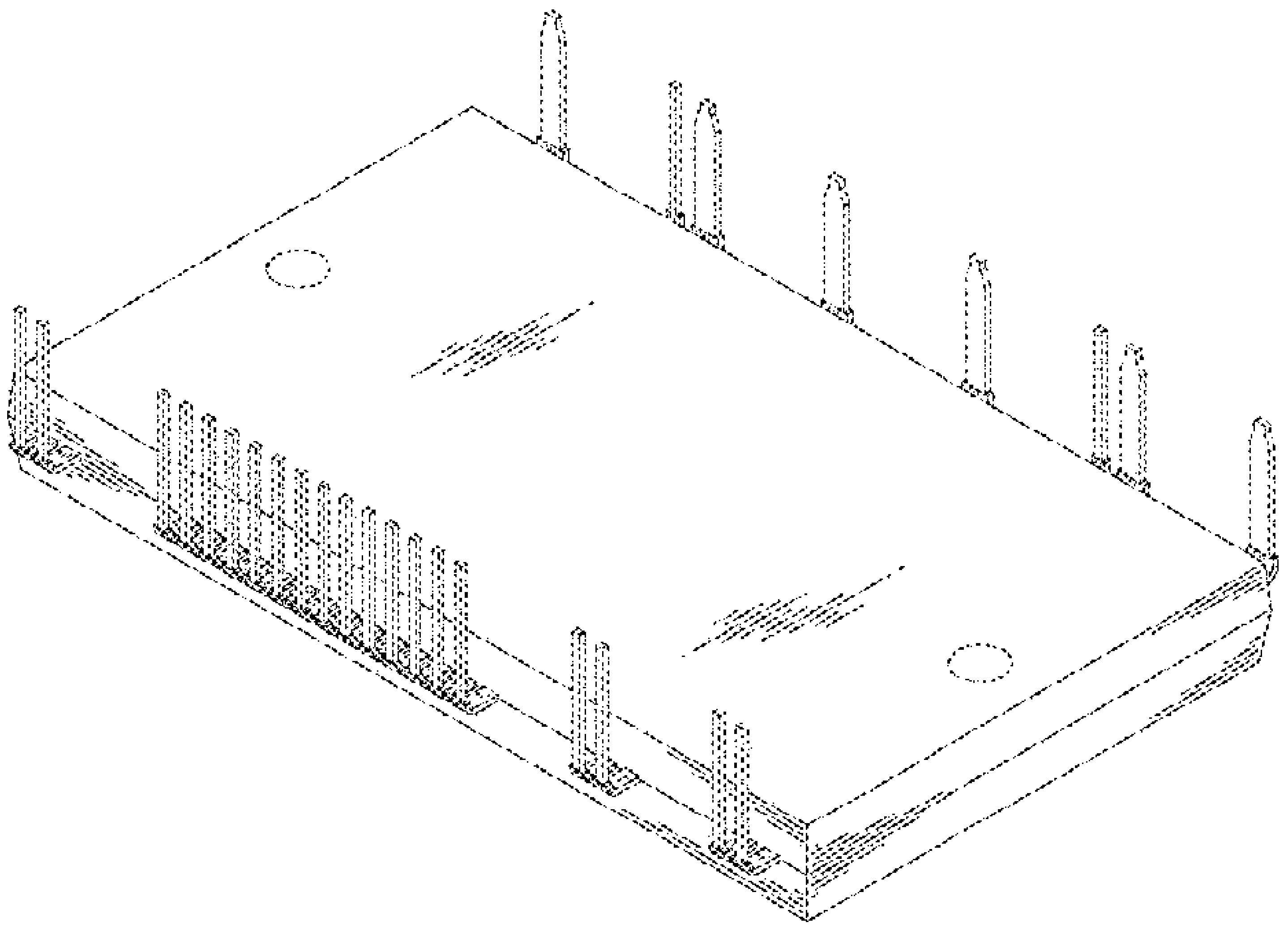


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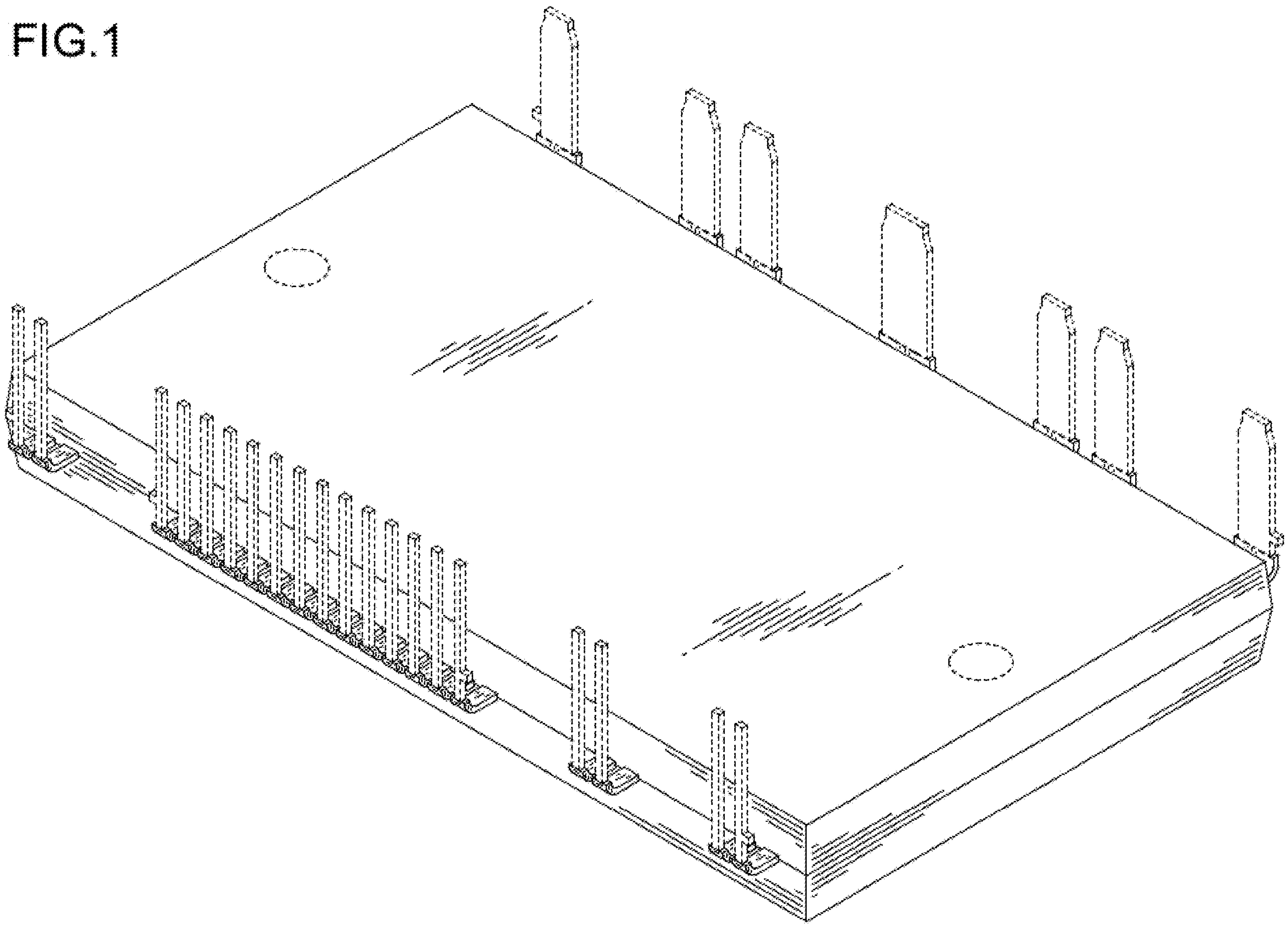
FIG.1



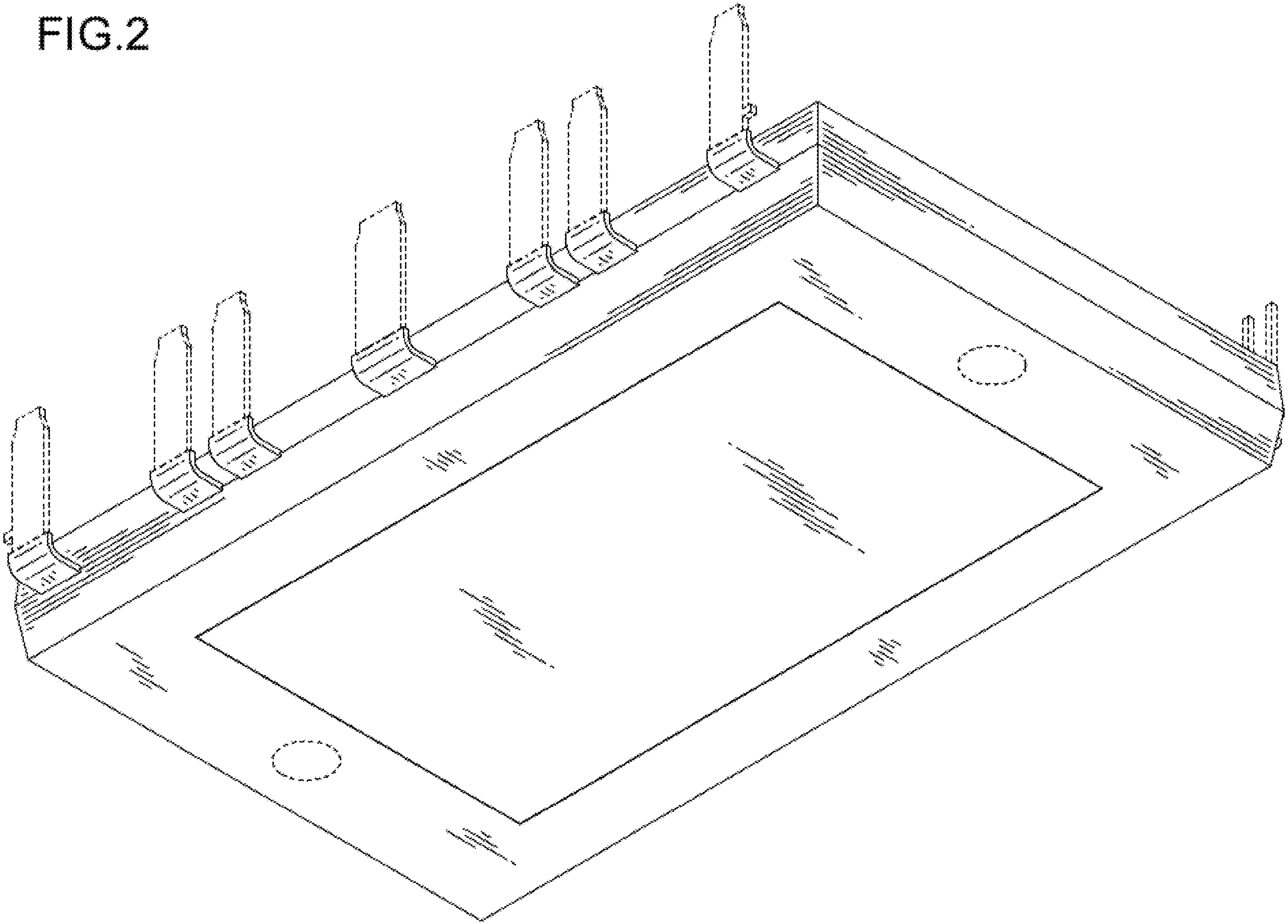


FIG.2

FIG.3

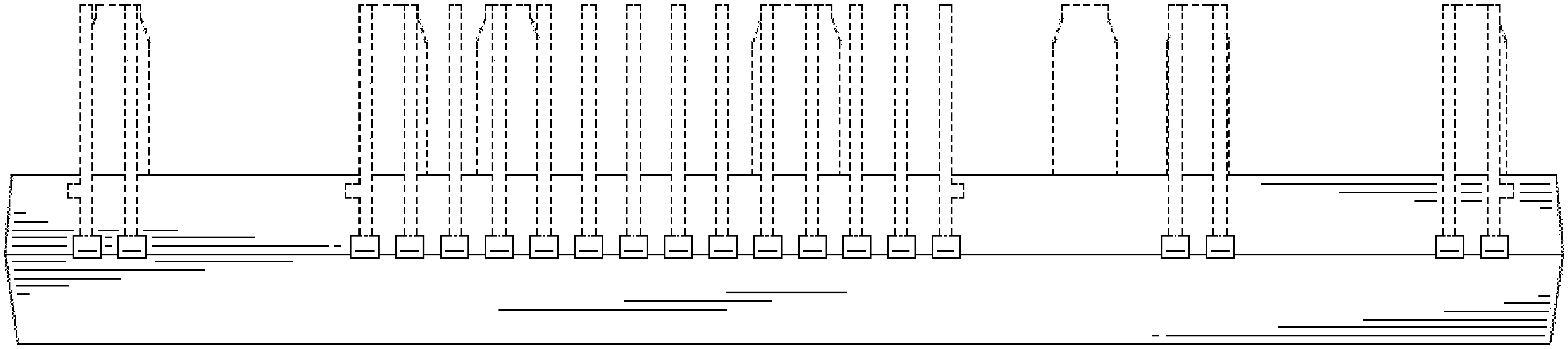


FIG.4

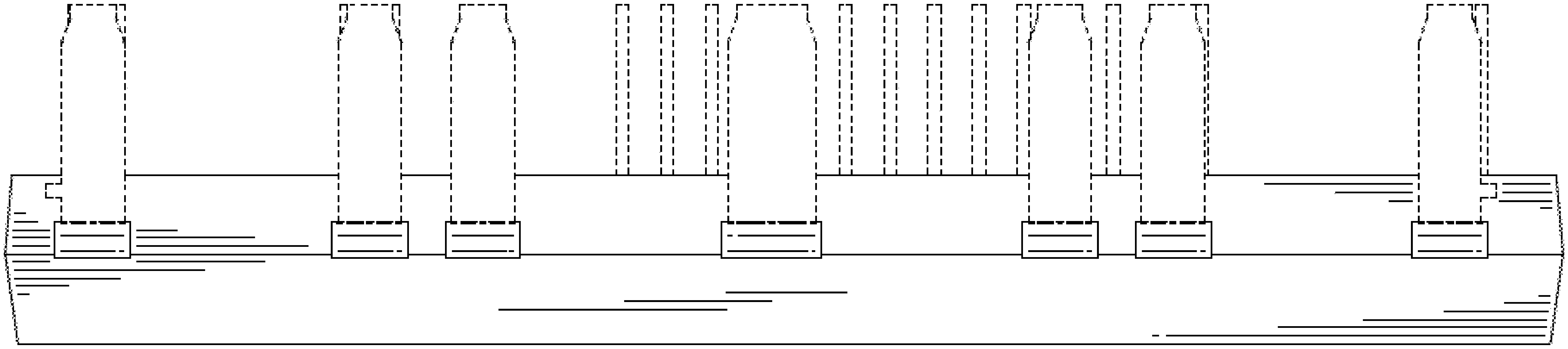
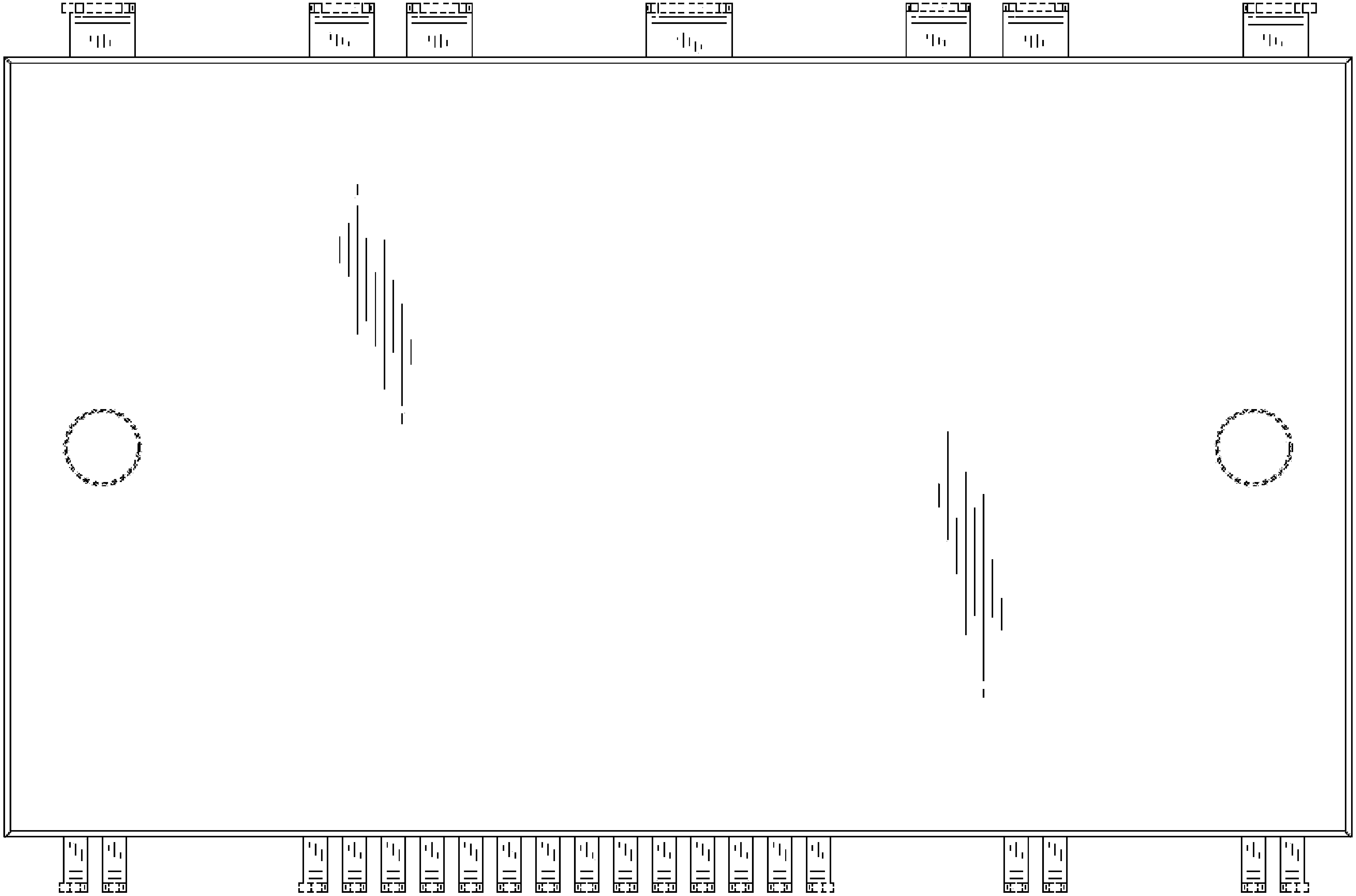


FIG.5



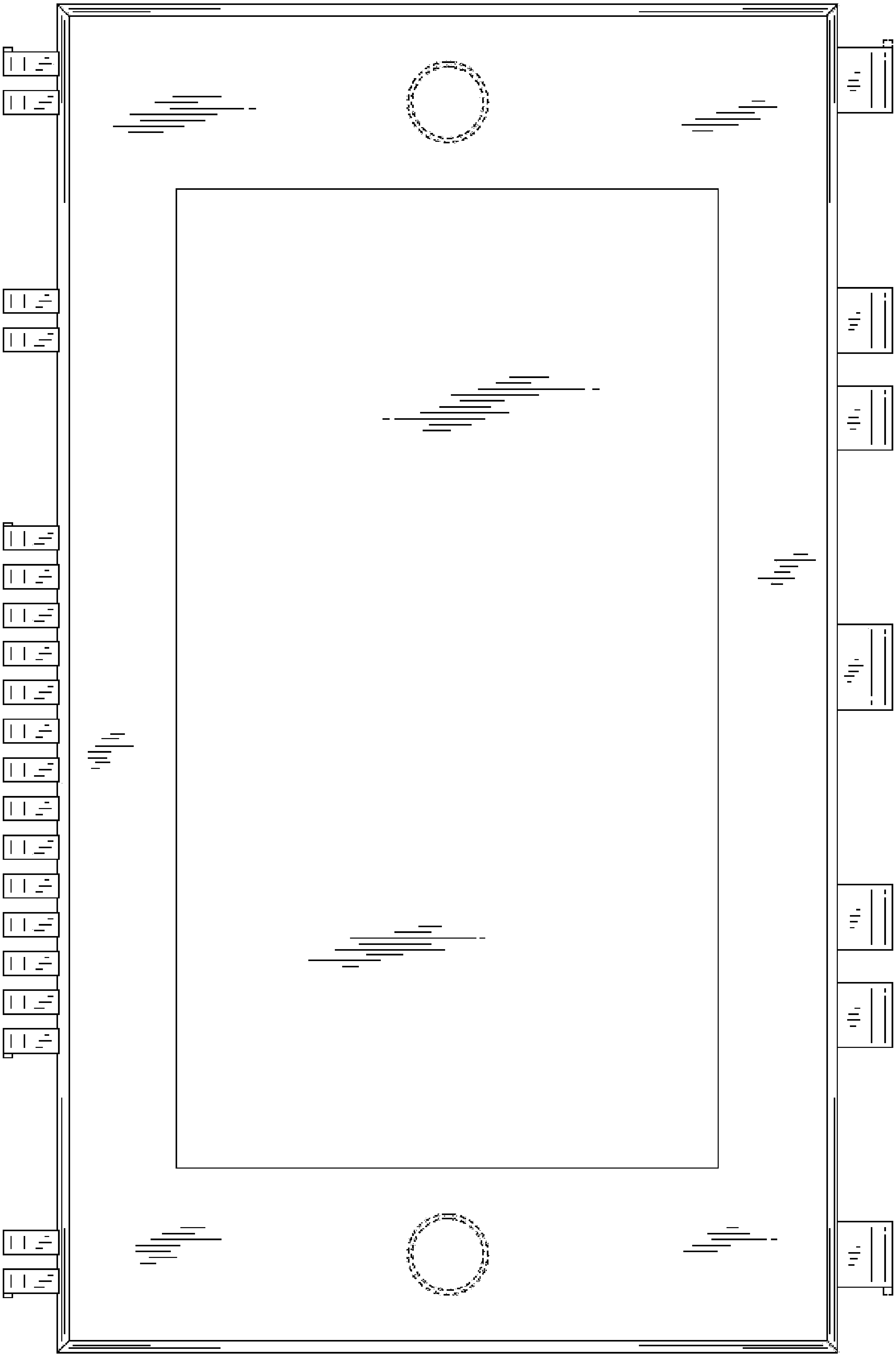


FIG.6

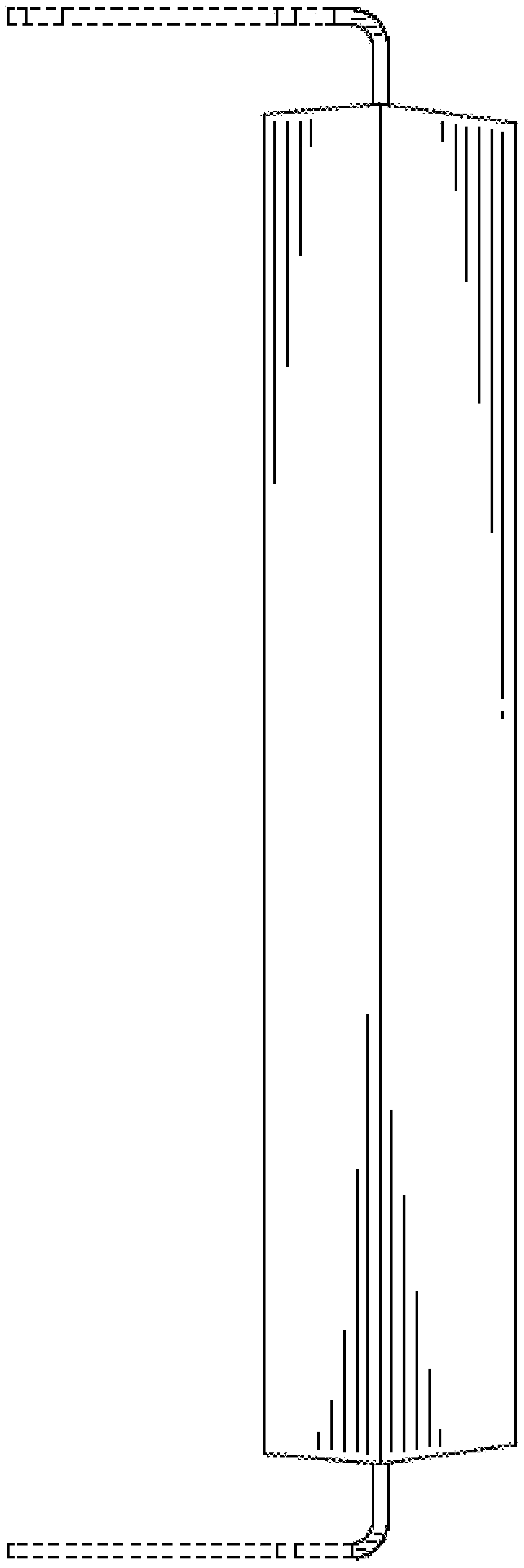


FIG.7

FIG.8

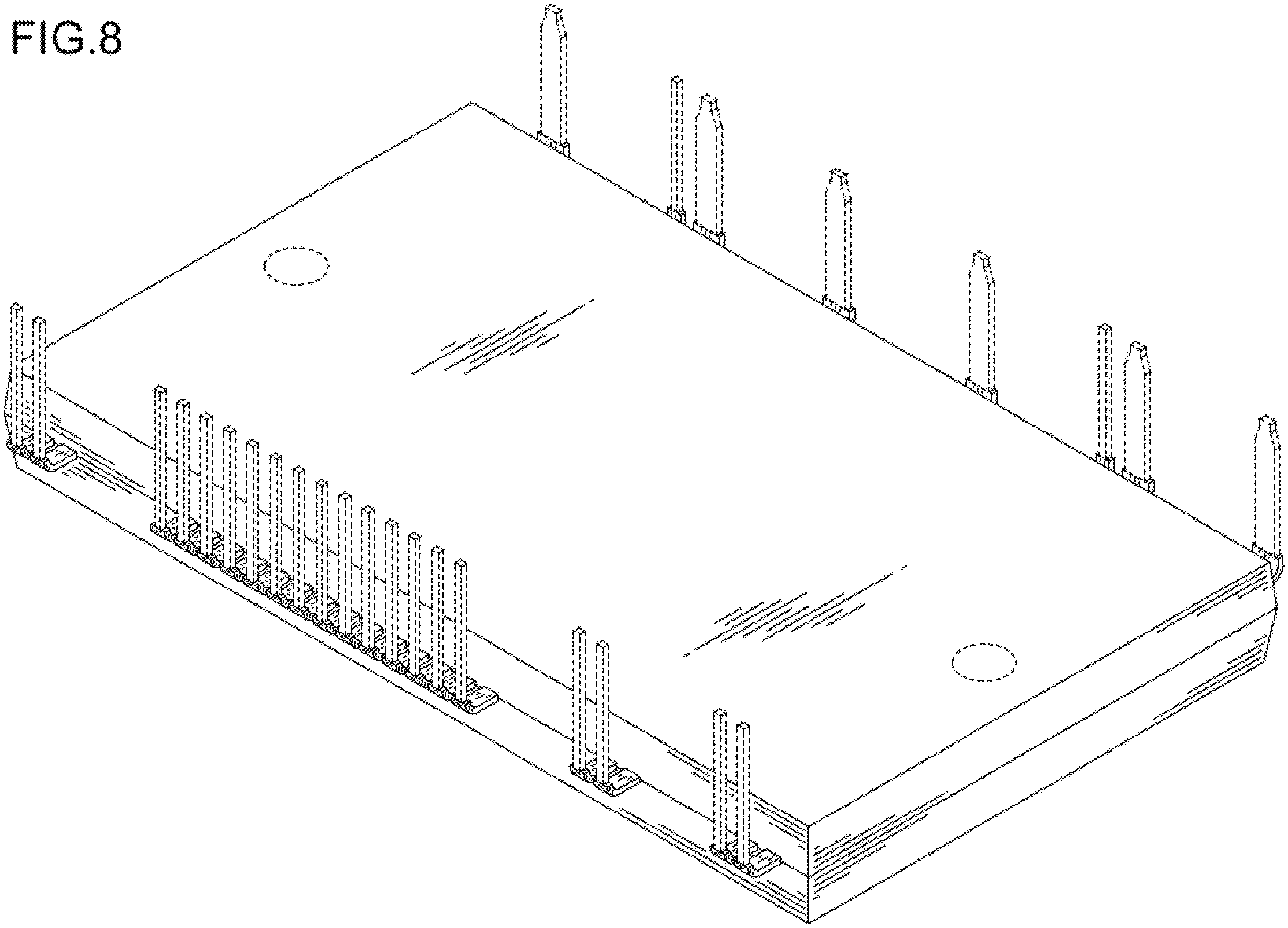


FIG.9

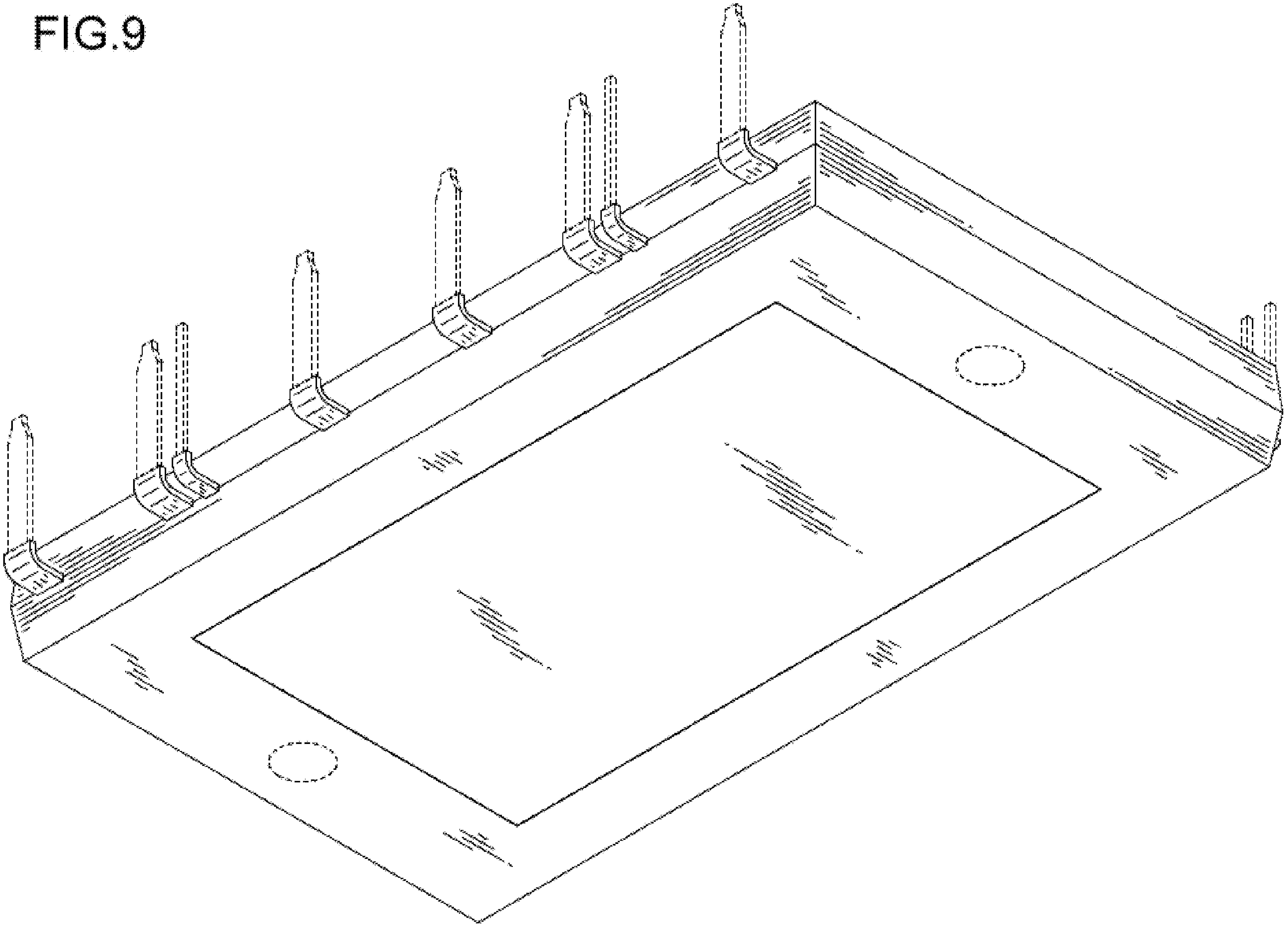


FIG. 10

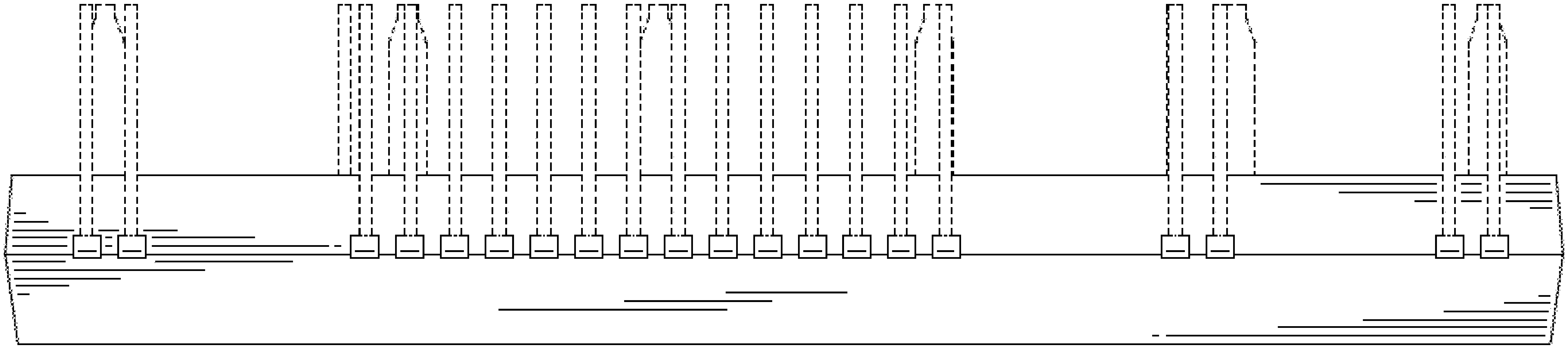


FIG.11

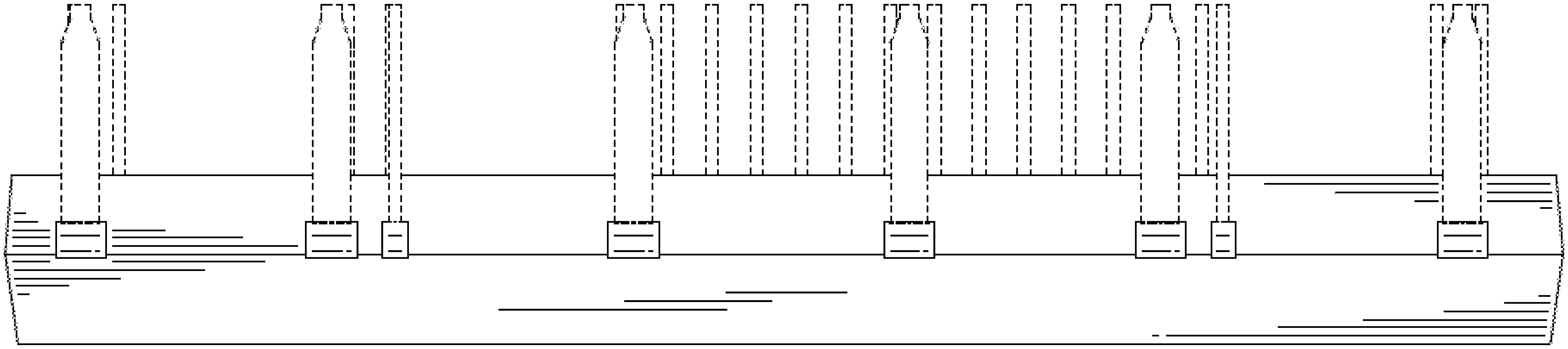
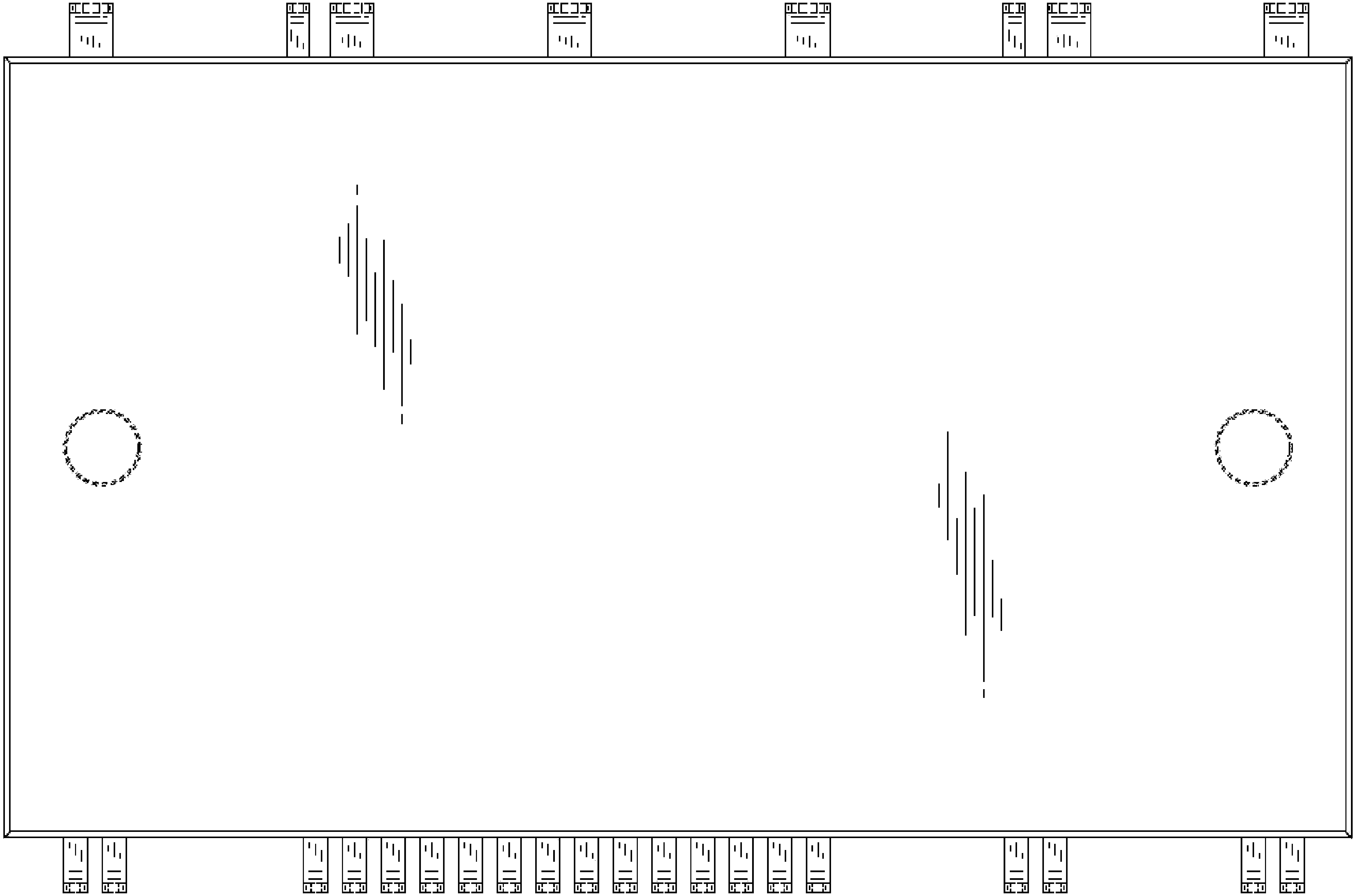


FIG.12



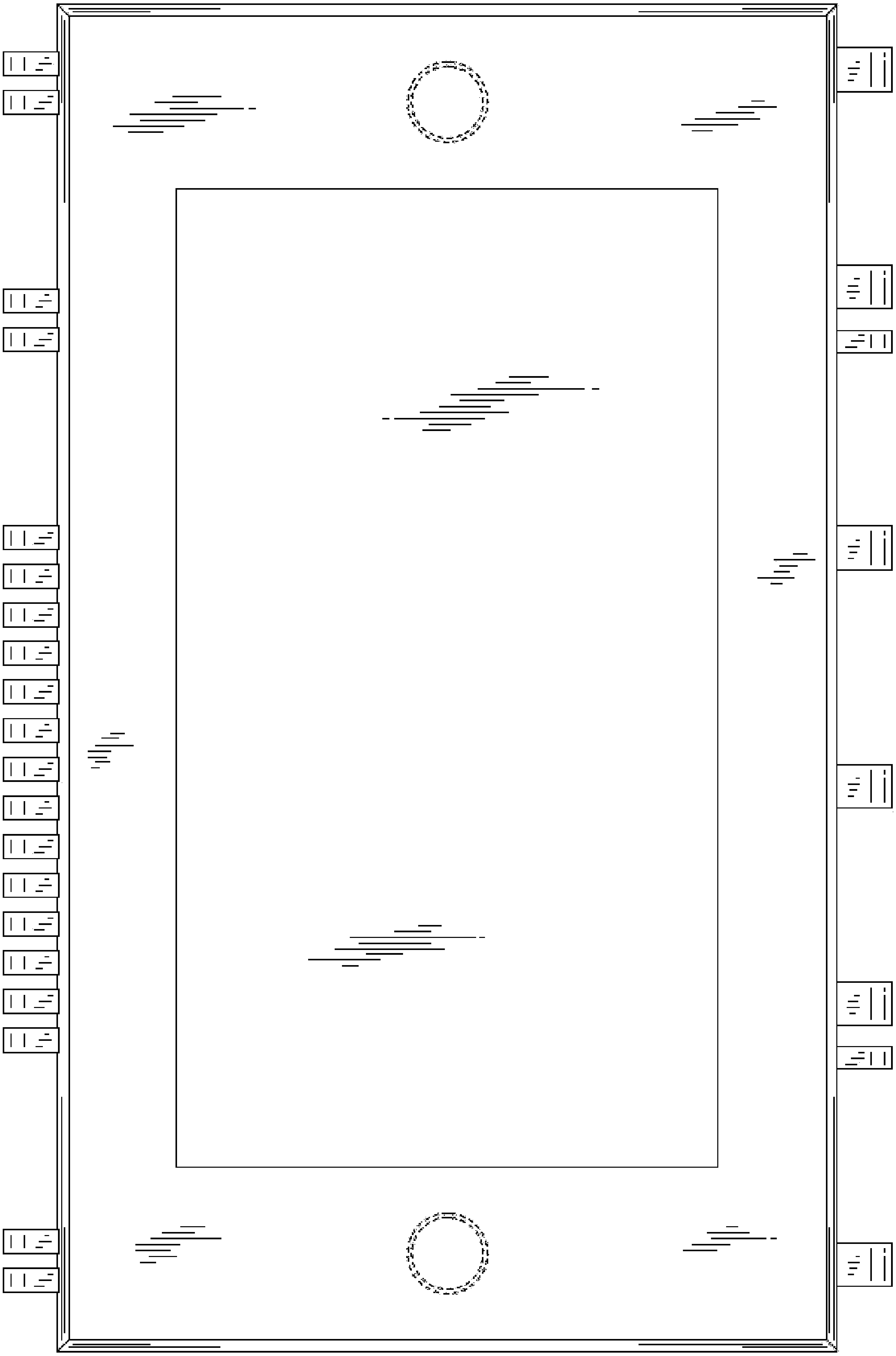


FIG.13

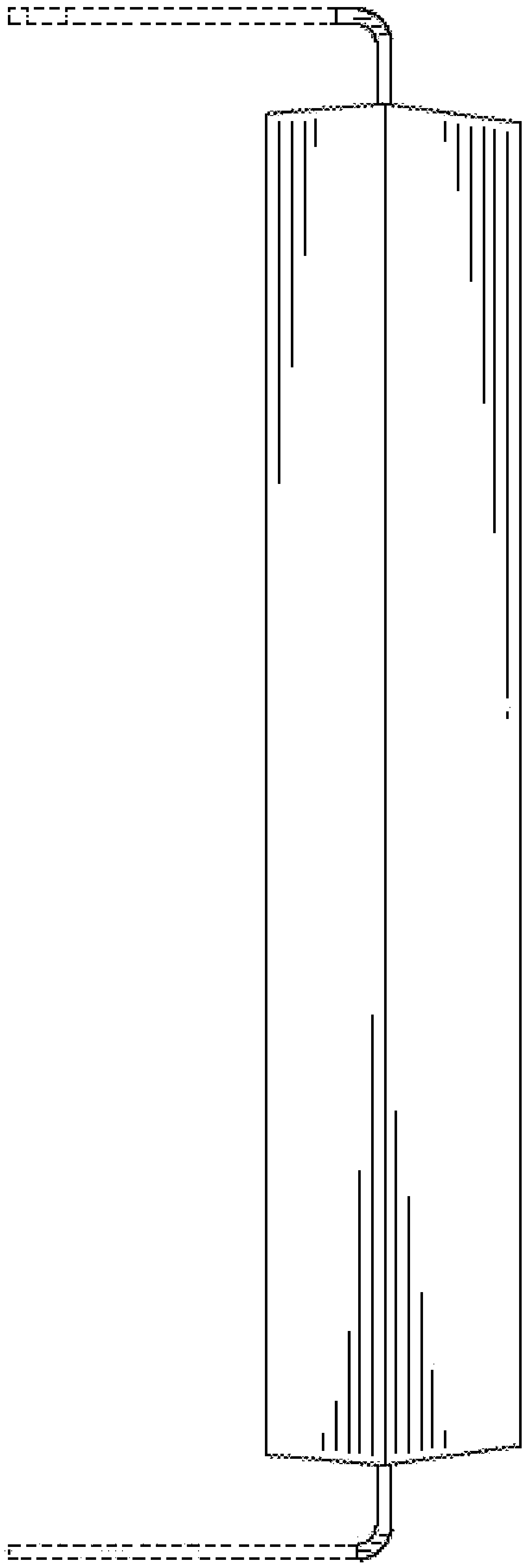


FIG. 14